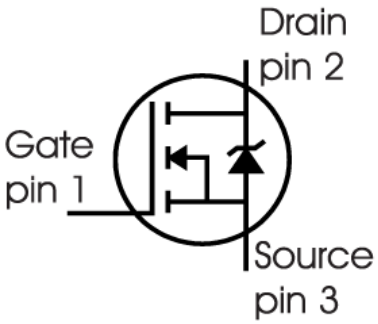
GSX47N50MF Super Junction MOSFETs

■**Description GroupSemiconductor(GS) has series** Multi-EPI **Super-Junction power MOSFET platforms for voltage up 500V to 1000 volts, both with design service and manufacturing capability, including cell, termination design and simulation.**
The GS 500V 47A power MOSFET is a Low voltage N channel Multi-EPI Super-Junction power MOSFET sample with advanced h technology to have better characteristics, such as fast switching time, low Ciss and Crss, low on resistance and excellent avalanche characteristics, making it especially suitable for applications which require superior power density and outstanding efficiency.



■ Features

- New revolutionary high voltage technology
- Better $R_{DS(on)}$ in TO-220F
- Ultra Low gate charge
- Periodic avalanche rated
- Extreme dv/dt rated
- Ultra low effective capacitances
- Pb-free lead planting
- Intrinsc fast-recovery body diode
- $R_{DS(ON)}$=0.08Ω @VGS = 10V

VDS = 500V
ID (@ VGS=10V) = 20A

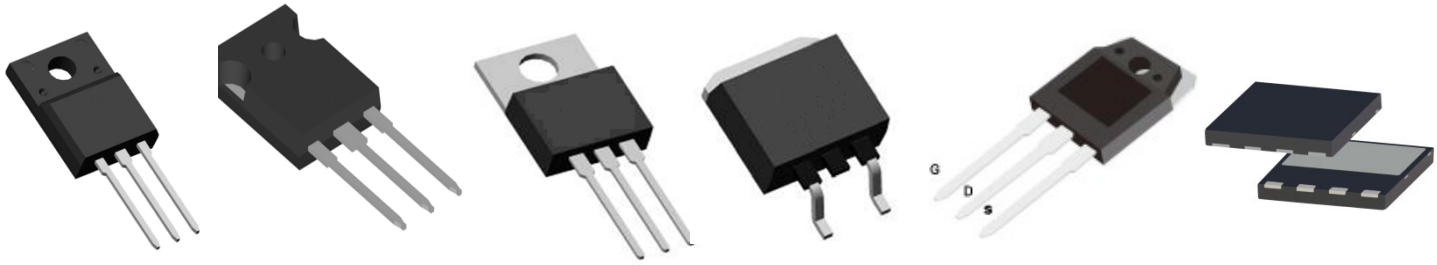
APPLICATIONS

- Consumer
- EV Charger
- PFC stages for server & telecom
- SMPS
- UPS
- Solar
- Lighting

ORDERING INFORMATION

Industrial Range: -40° C to +125° C

Order Part No.	Package
GSA47N50MF	TO-220F, Pb-Free
GSW47N50MF	TO-247, Pb-Free
GSB47N50MF	TO-263, Pb-Free
GSP47N50MF	TO-220, Pb-Free
GSJ47N50MF	TO-3P, Pb-Free
GSN47N50MF	DFN 8*8 Pb-Free



TO-220F TO-247 TO-220 TO-263 TO-3P DFN8*8

GROUP
SEMICONDUCTOR

GSX47N50MF Super Junction MOSFETs

Maximum rating sat Tj = 25 ℃ , unlessotherwise specified.

Symbol	Parameter	GSX47N50MF	Unit
V_{DSS}	Drain-Source Voltage	500	V
I_D	Drain Current -Continuous (TC = 25℃) -Continuous (TC = 100℃)	47* 29*	A
I_{DM}	Drain Current - Pulsed (Note 1)	140	A
V_{GSS}	Gate-Source voltage	±30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	1160	mJ
I_{AR}	Repetitive Avalanche Current (Note 1)	10	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	1.72	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	15	V/ns
dVds/dt	Drain Source voltage slope (Vds=400V)	50	V/ns
P_D	Power Dissipation (TC = 25℃)	391	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	℃
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8” from Case for 5 Seconds	300	℃

1) Limited by Tj,max. Maximum duty cycle D=0.75
2) Pulse width tp limited by Tj,max
3) Identical low side and high side switch with identical RG; Vpeak<V(BR)DSS ; Tj<Tj.max

Thermal Characteristics

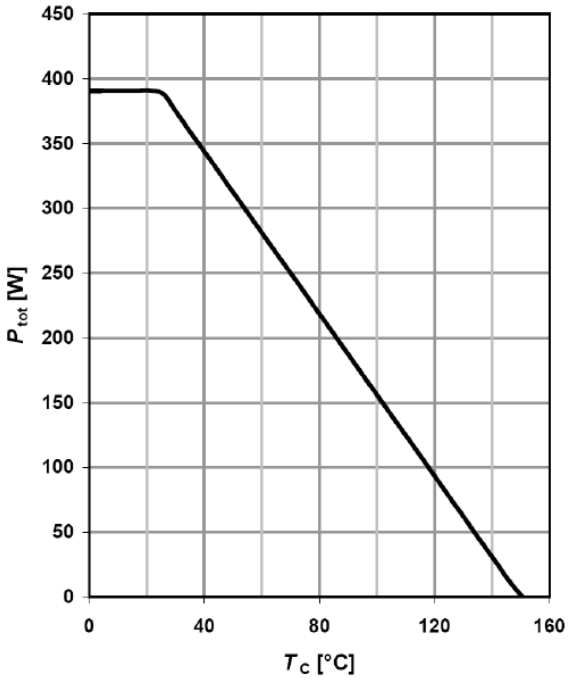
Symbol	Parameter	GSX47N50MF	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.32	℃/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	℃/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	℃/W

GSX47N50MF Super Junction MOSFETs

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250μA, T_J = 25℃	500	-	-	V
		V_{GS} = 0V, I_D = 250μA, T_J = 150℃	-	550	-	V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	I_D = 250μA, Referenced to 25℃	-	0.6	-	V/℃
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 500V, V_{GS} = 0V Tj=25℃ -T_J = 150℃	-	6 50	- -	μA μA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = 30V, V_{DS} = 0V	-	-	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -30V, V_{DS} = 0V	-	-	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	2.5	-	4.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = 10V, I_D = 23A	-	70	80	mΩ
g_{FS}	Forward Transconductance	V_{DS} = 40V, I_D = 25A	-	30	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz	-	3100	-	pF
C_{oss}	Output Capacitance		-	148	-	pF
C_{rss}	Reverse Transfer Capacitance		-	5	-	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 400V, I_D = 23A R_G = 20Ω (Note 4)	-	19	-	ns
t_r	Turn-On Rise Time		-	10	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	87	-	ns
t_f	Turn-Off Fall Time		-	5	-	ns
Q_g	Total Gate Charge	V_{DS} = 400V, I_D = 23A V_{GS} = 10V (Note 4)	-	190	-	nC
Q_{gs}	Gate-Source Charge		-	30	-	nC
Q_{gd}	Gate-Drain Charge		-	95	-	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		-	-	47	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-	-	140	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0V, I_S = 23A	-	0.9	1.5	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0V, I_S = 23A dIF/dt =100A/μs	-	210	-	ns
Q_{rr}	Reverse Recovery Charge		-	1.2	-	μC

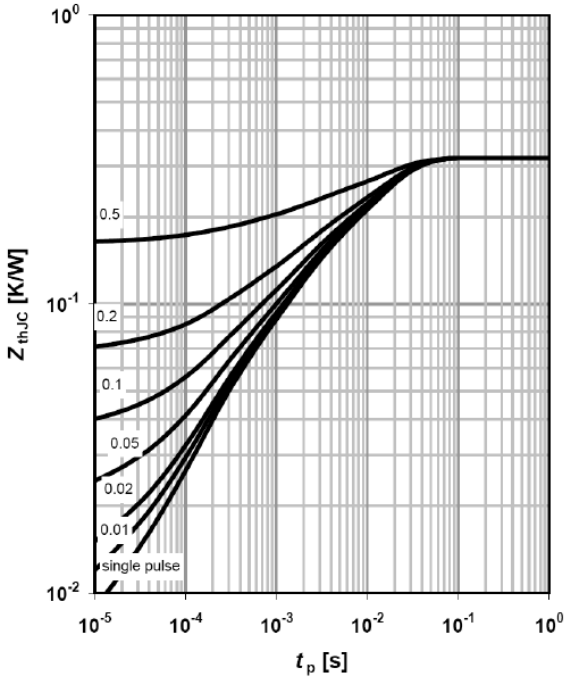
1) Co(er) is a fixed capacitance that gives the same stored energy as Coss while VDS is rising from 0 to 80% V(BR)DSS
2) Co(tr) is a fixed capacitance that gives the same charging time as Coss while VDS is rising from 0 to 80% V(BR)DSS

Power dissipation



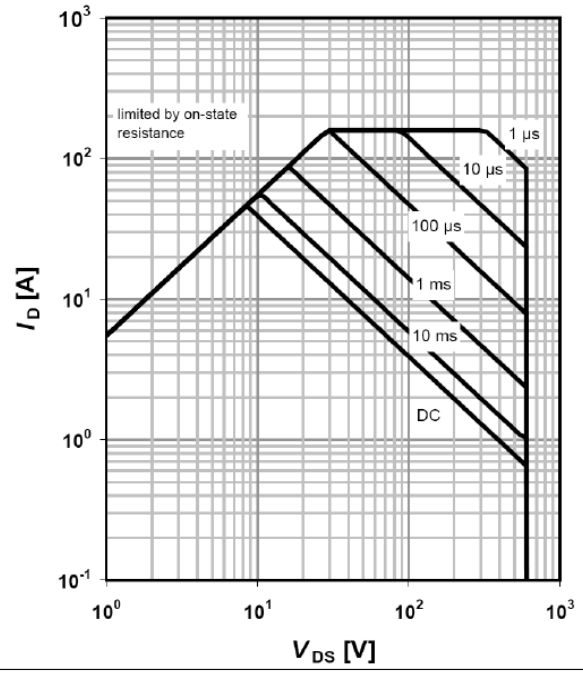
P_{tot} = f(T_C)

Max. transient thermal impedance



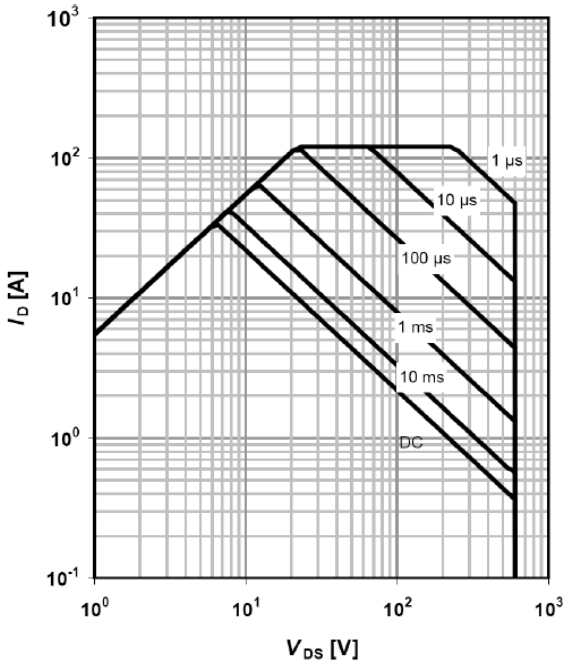
$Z_{(thJC)}$=f(tp); parameter: D=t_p/T

Safe operating area T_C=25 °C



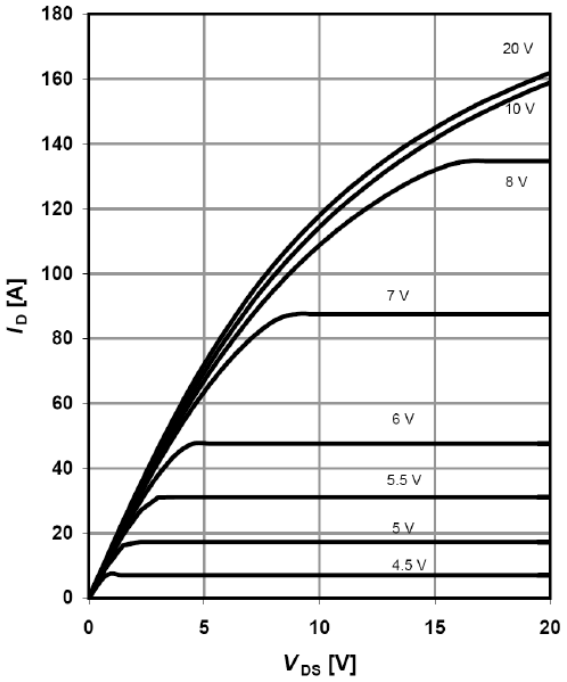
I_D=f(V_{DS}); T_C=25 °C; V_{GS} > 7V; D=0; parameter t_p

Safe operating area T_C=80 °C



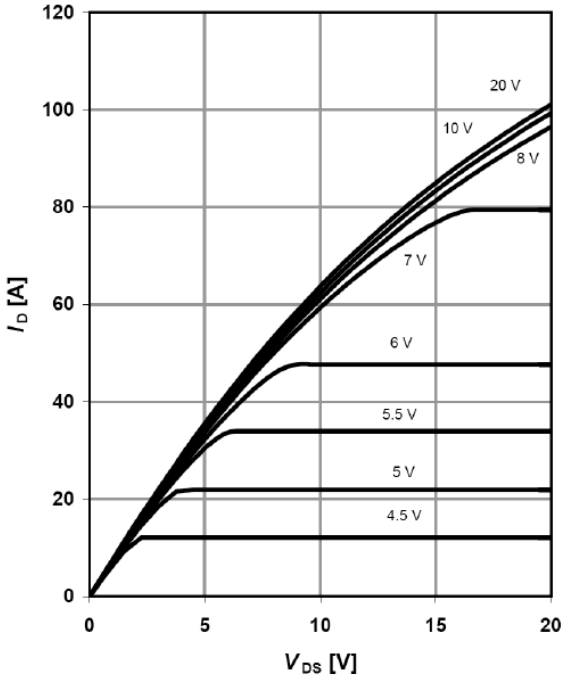
I_D=f(V_{DS}); T_C=80°C; V_{GS} > 7V; D=0; parameter t_p

Typ. output characteristics T_j=25 °C



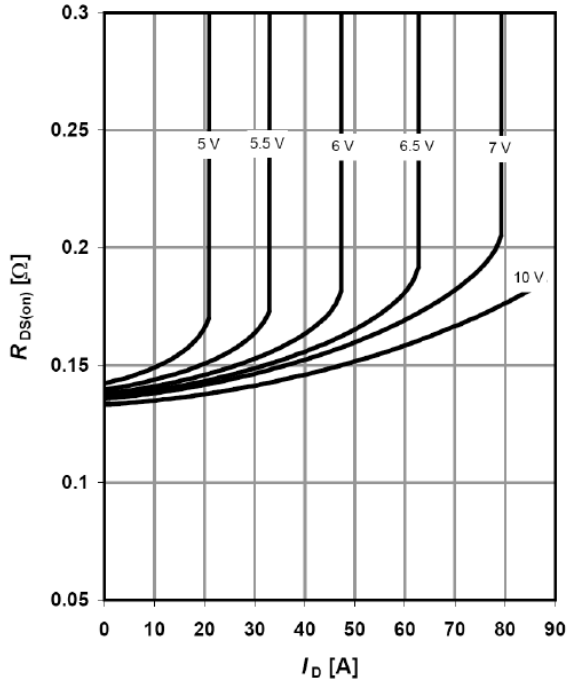
I_D=f(V_{DS}); T_j=25 °C; parameter: V_{GS}

Typ. output characteristics T_j=125 °C



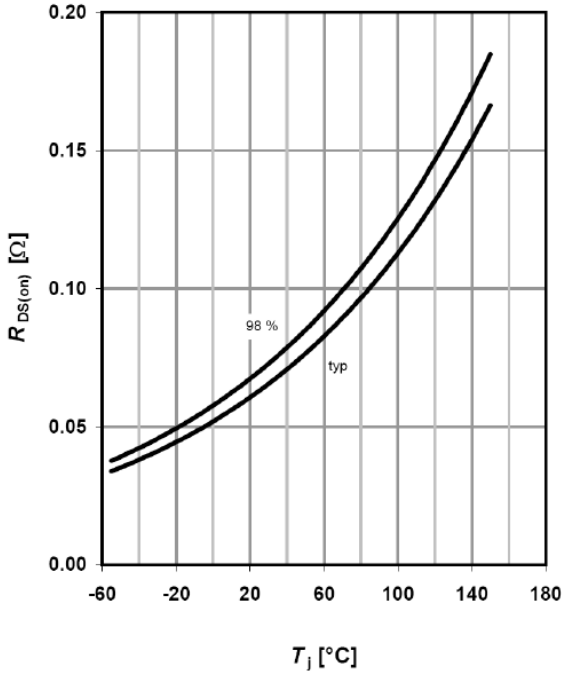
I_D=f(V_{DS}); T_j=125 °C; parameter: V_{GS}

Typ. drain-source on-state resistance



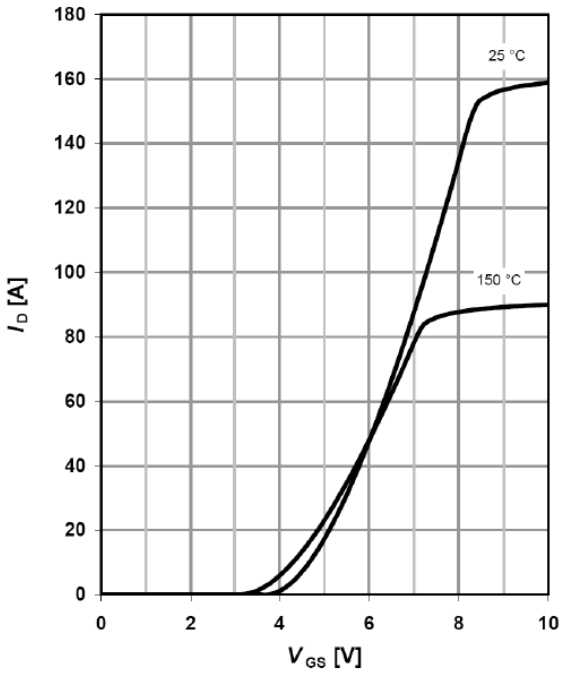
$R_{DS(on)}$=f(I_D); T_j=125 °C; parameter: V_{GS}

Drain-source on-state resistance



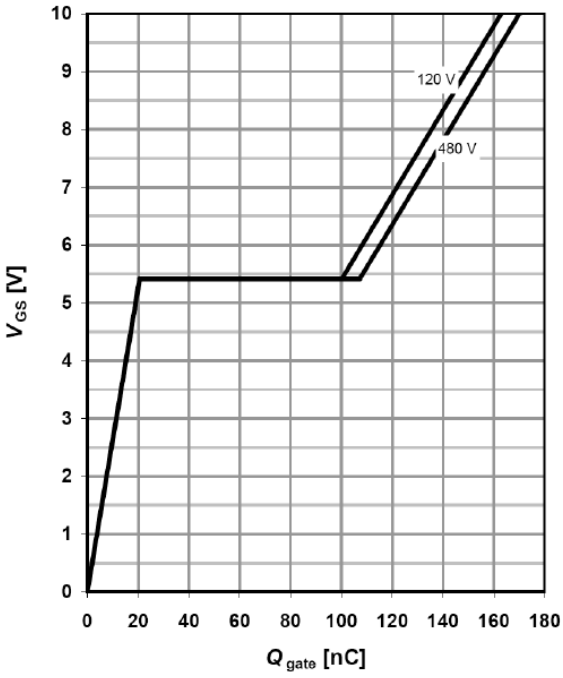
$R_{DS(on)}$=f(T_j); I_D=17.6 A; V_{GS}=10 V

Typ. transfer characteristics



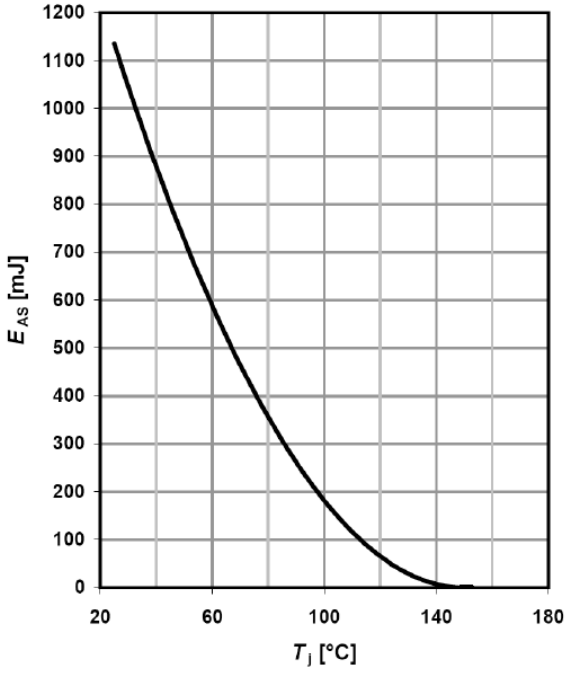
I_D=f(V_{GS}); V_{DS}=20V

Typ. gate charge



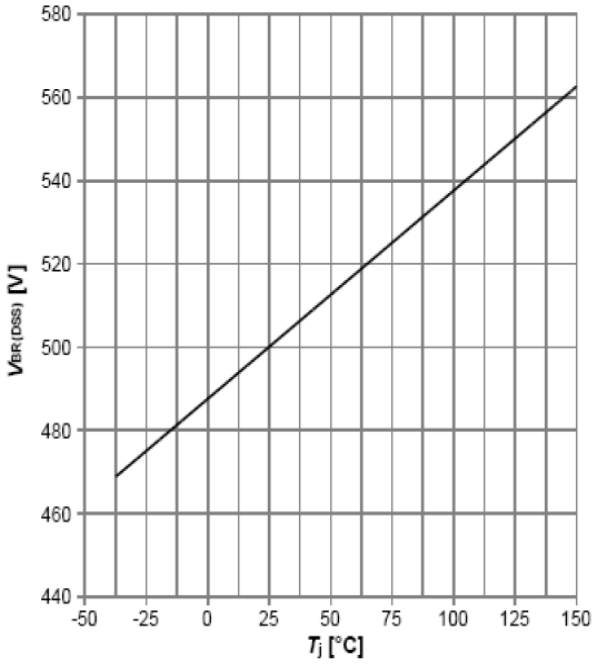
V_{GS}=f(Q_{gate}), I_D=26.3 A pulsed

Avalanche energy



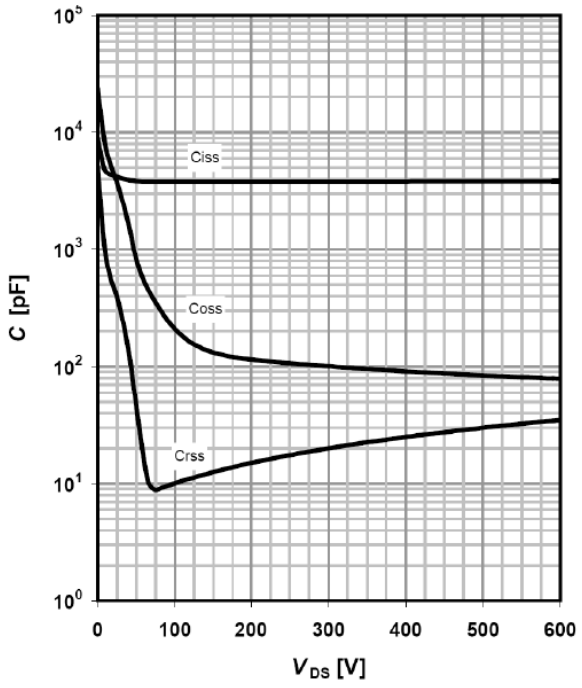
E_{AS}=f(T_j); I_D=9.3 A; V_{DD}=50 V

Drain-source breakdown voltage



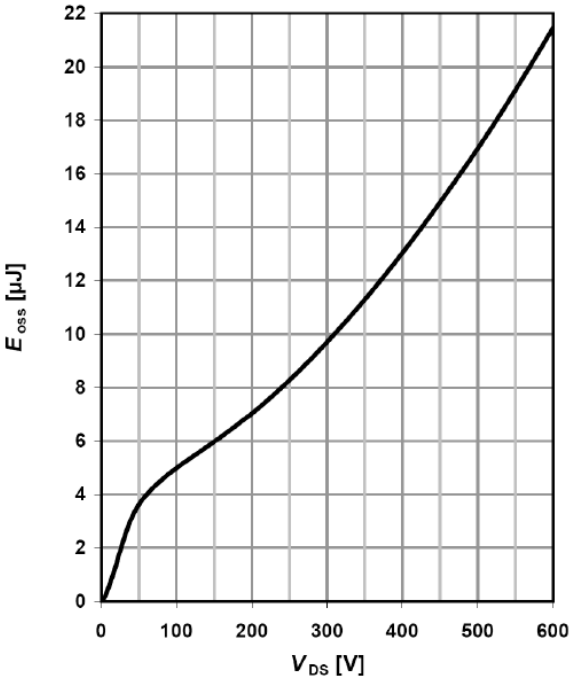
$V_{BR(DSS)}$=f(T_j); I_D=1.0 mA

Typ. capacitances



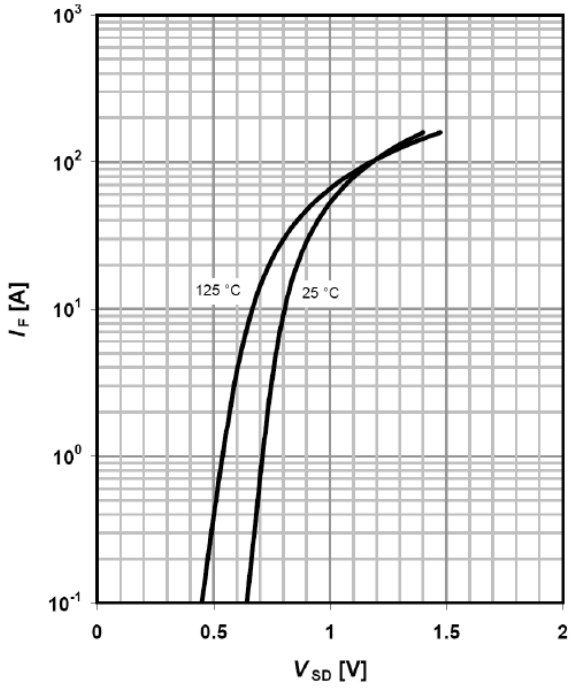
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Typ. C_{oss} stored energy



E_{oss}=f(V_{DS})

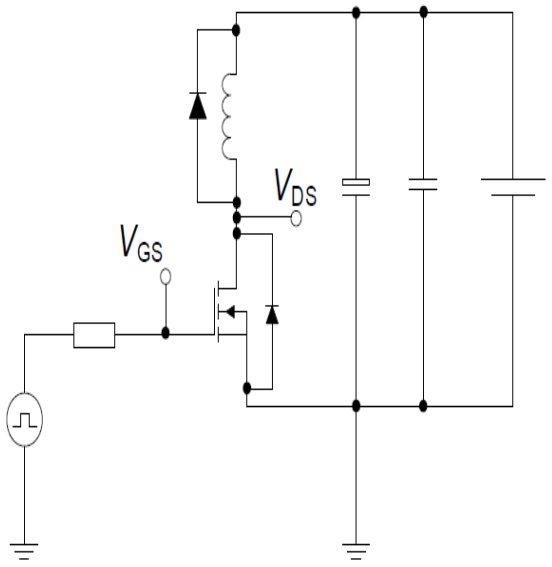
Forward characteristics of reverse diode



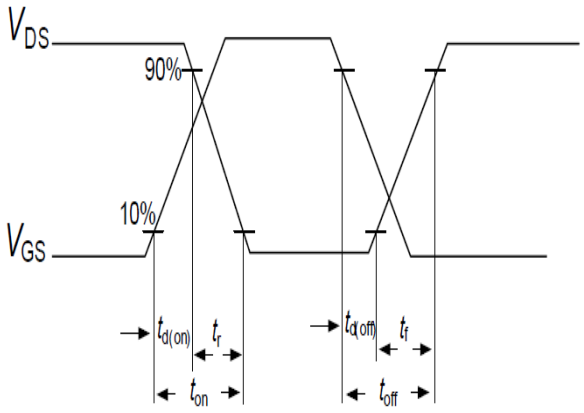
I_F=f(V_{SD}); parameter: T_j

Switching times test circuit and waveform for inductive load

Switching times test circuit for inductive load

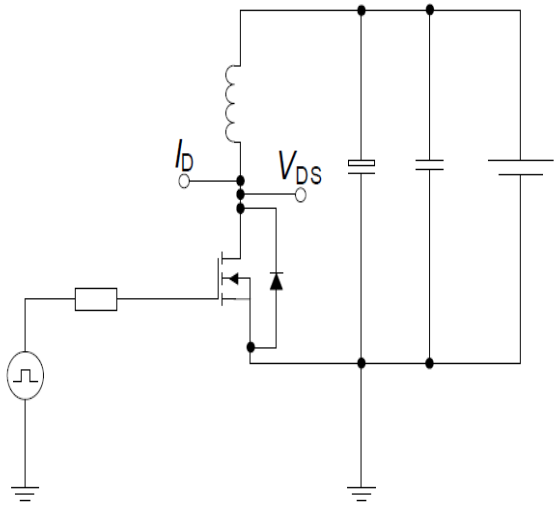


Switching time waveform

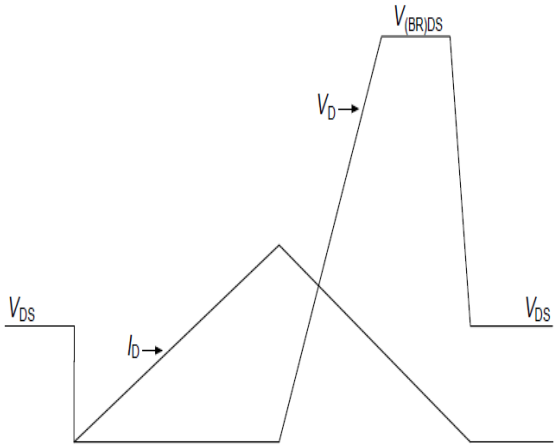


Unclamped inductive load test circuit and waveform

Unclamped inductive load test circuit

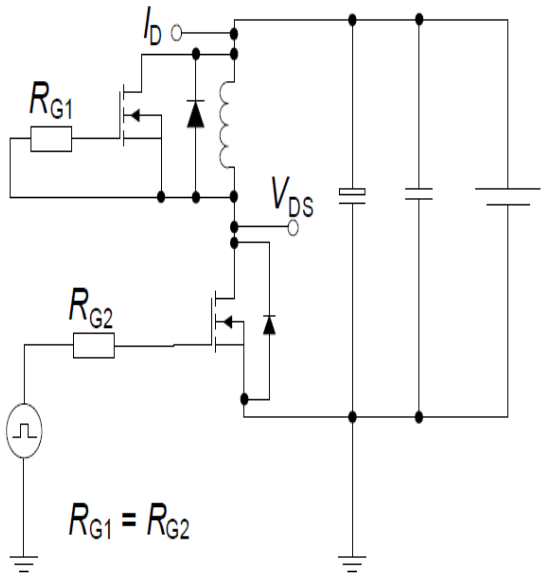


Unclamped inductive waveform

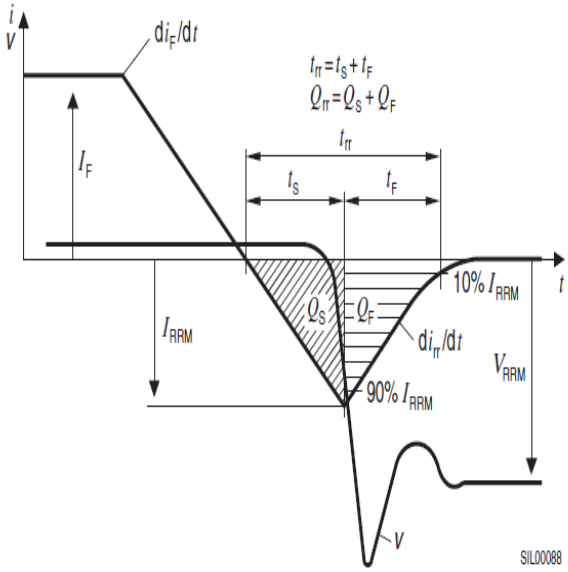


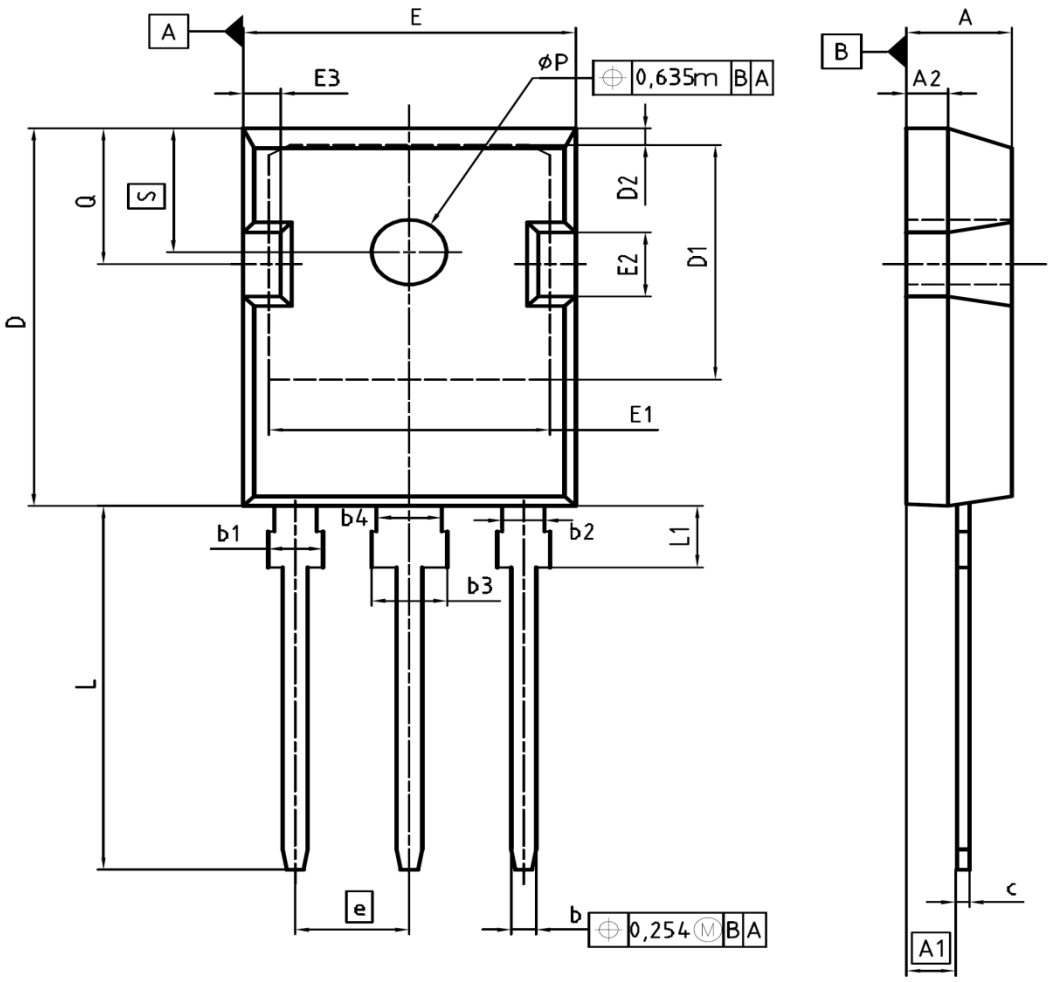
Test circuit and waveform for diode characteristics

Test circuit for diode characteristics



Diode recovery waveform





DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.27	2.54	0.089	0.100
A2	1.85	2.16	0.073	0.085
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	5.44		0.214	
N	3		3	
L	19.80	20.32	0.780	0.800
L1	4.10	4.47	0.161	0.176
øP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

DOCUMENT NO.
Z8B00003327

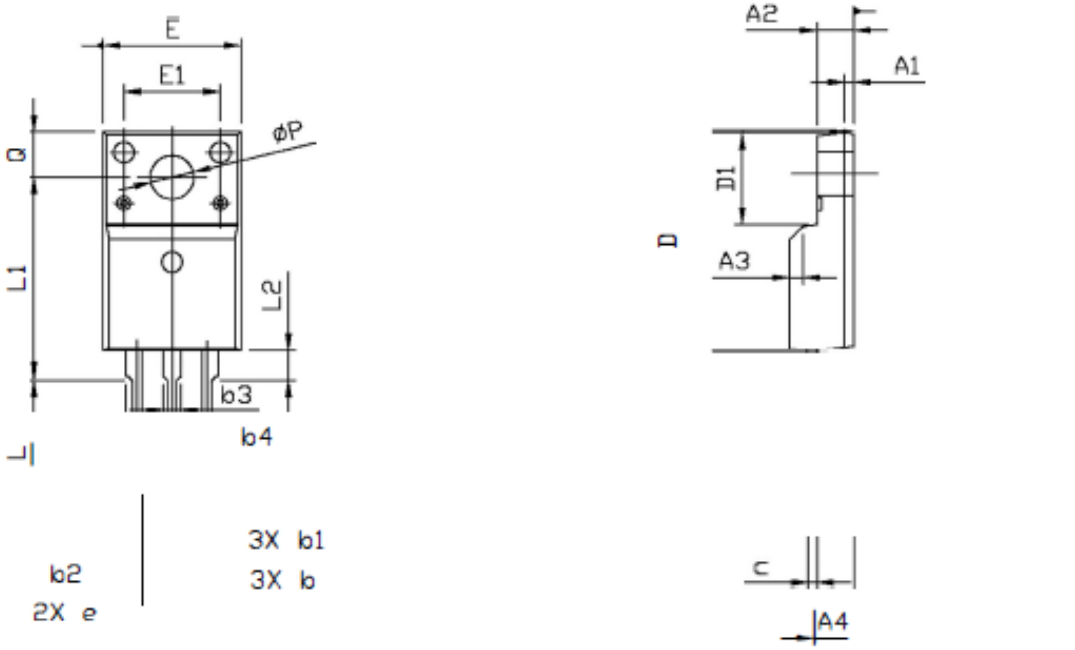
SCALE 0 5 5 7.5mm

EUROPEAN PROJECTION

ISSUE DATE
01-10-2009

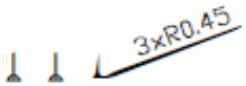
REVISION
04

TO220F PACKAGE OUTLINE



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.50	4.70	4.90	0.177	0.185	0.193
A1		0.70			0.028	
A2	2.34	2.54	2.74	0.092	0.100	0.108
A3		1X45°			1X45°	
A4	2.66	2.76	2.86	0.105	0.106	0.113
b	0.59	0.69	0.79	0.023	0.027	0.031
b1	0.25	0.35	0.45	0.010	0.014	0.018
b2	1.14	1.24	1.29	0.045	0.049	0.051
b3	1.28	1.38	1.43	0.050	0.054	0.056
b4		1.40 MIN.			0.055 MIN.	
c	0.59	0.64	0.74	0.023	0.025	0.029
D	15.67	15.87	16.07	0.617	0.625	0.633
D1	6.48	6.68	6.88	0.255	0.263	0.271
e		2.54 BSC			0.100 BSC.	
E	9.96	10.16	10.36	0.392	0.400	0.408
E1		7.00			0.276	
E2	9.26	9.46	9.66	0.365	0.372	0.380
L	10.76	10.96	11.16	0.424	0.431	0.439
L1	14.39	14.59	14.79	0.567	0.574	0.582
L2	1.70	2.03	2.20	0.067	0.080	0.087
Q	3.20	3.30	3.40	0.126	0.130	0.134
øP	3.08	3.18	3.28	0.121	0.125	0.129

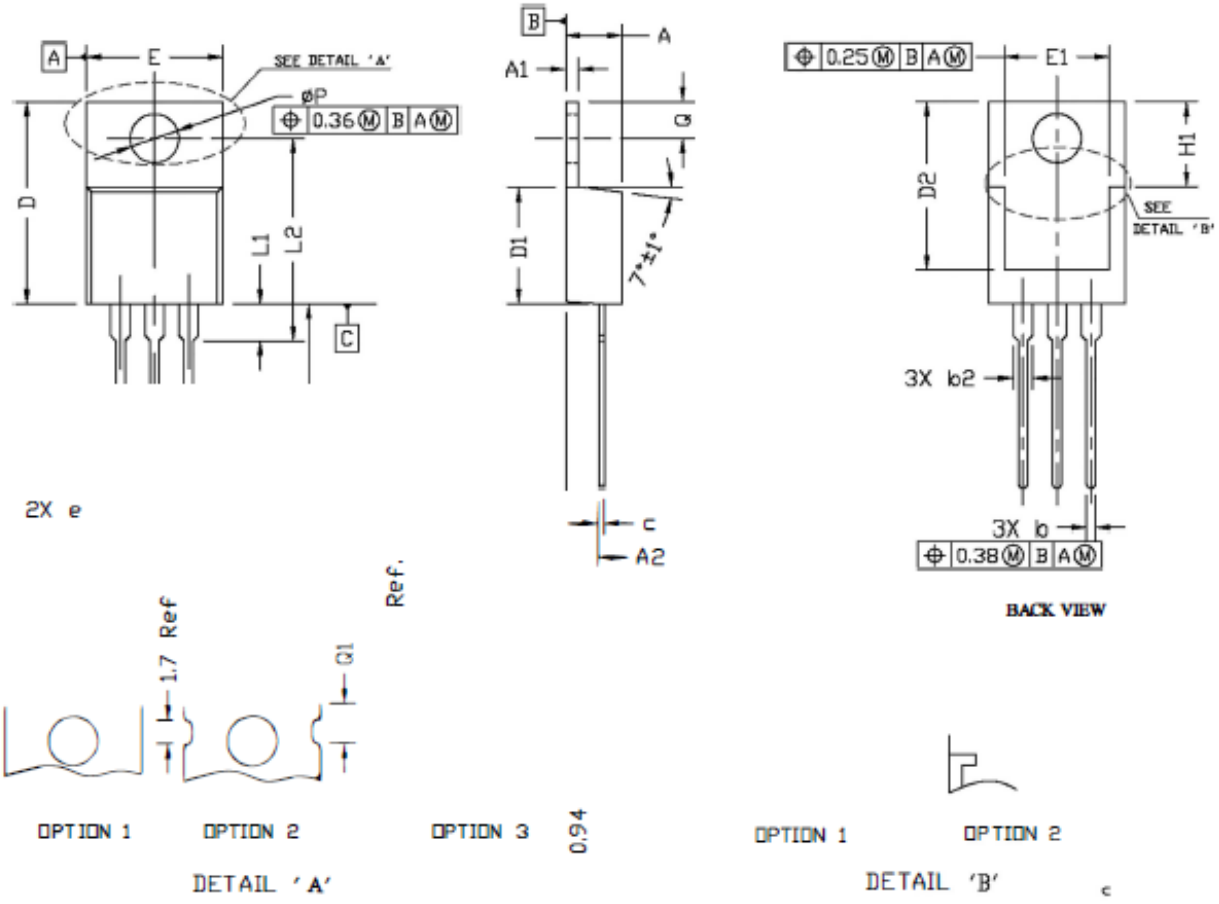
RECOMMENDATION OF HOLE PATTERN



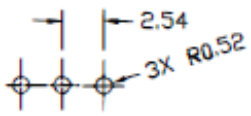
UNIT: mm

NOTE
1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
   MOLD FLASH SHOULD BE LESS THAN 6 MIL.
2. TOLERANCE 0.100 MILLIMETERS UNLESS OTHERWISE SPECIFIED.
3. CONTROLLING DIMENSION IS MILLIMETER.
   CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

TO220 PACKAGE OUTLINE



RECOMMENDATION OF HOLE PATTERN

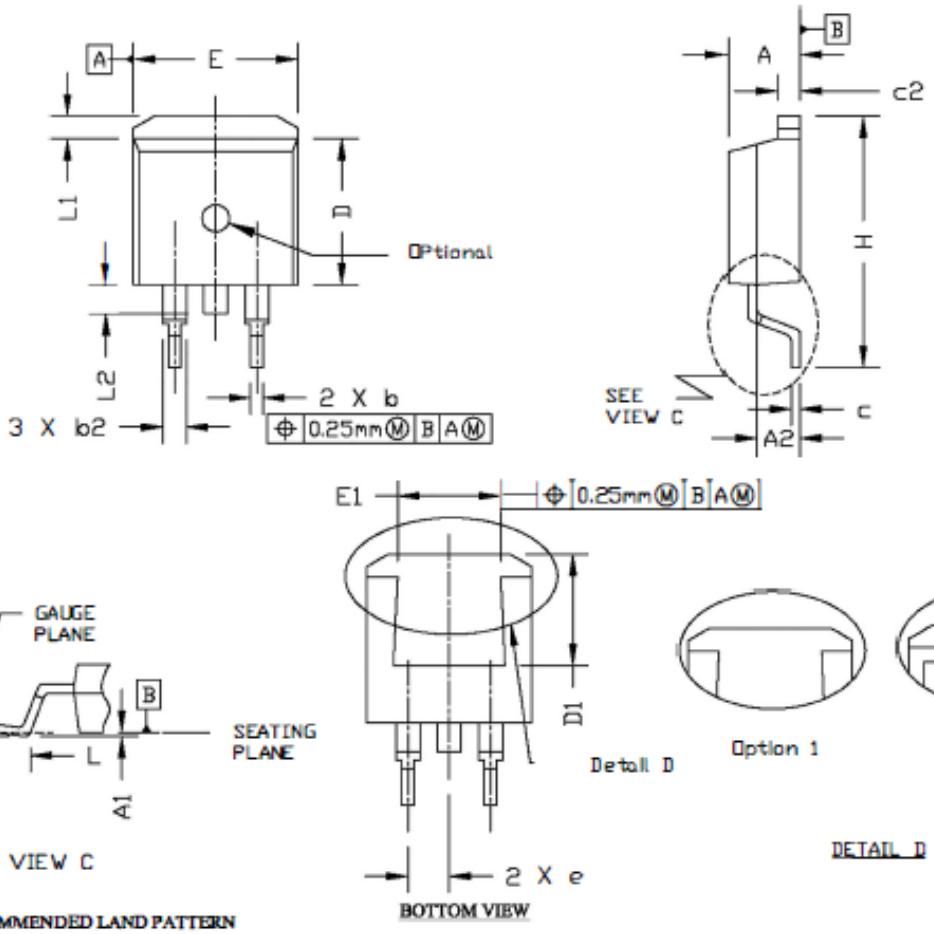


UNIT: mm

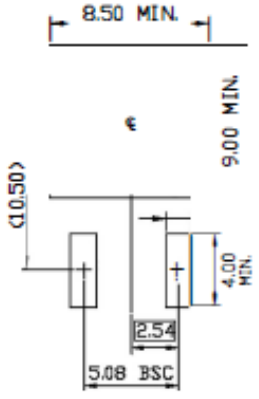
SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.30	4.45	4.72	0.169	0.175	0.186
A1	1.15	1.27	1.40	0.045	0.050	0.055
A2	2.20	2.67	2.90	0.087	0.105	0.114
b	0.69	0.81	0.95	0.027	0.032	0.037
b2	1.17	1.37	1.45	0.046	0.050	0.068
c	0.36	0.38	0.60	0.014	0.015	0.024
D	14.50	15.44	15.80	0.571	0.608	0.622
D1	8.59	9.14	9.65	0.338	0.360	0.380
D2	11.43	11.73	12.48	0.450	0.462	0.491
e		2.54 BSC			0.100 BSC.	
E	9.66	10.03	10.54	0.380	0.395	0.415
E1	6.22			0.245		
H1	6.10	6.30	6.50	0.240	0.248	0.256
L	12.27	12.82	14.27	0.483	0.505	0.562
L1	2.47		3.90	0.097		0.154
L2			16.70			0.657
Q	2.59	2.74	2.89	0.102	0.108	0.114
øP	3.50	3.84	3.89	0.138	0.151	0.153
Q1	2.70		2.90	0.106		0.114

NOTE
1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH SHOULD BE LESS THAN 6 MIL.
2. TOLERANCE 0.100 MILLIMETERS UNLESS OTHERWISE SPECIFIED.
3. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

TO263(D2PAK) PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



UNIT: mm

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.064	4.45	4.826	0.160	0.175	0.190
A1	0.00		0.254	0.000		0.010
A2	2.20	2.67	2.90	0.087	0.105	0.114
b	0.508	0.81	0.991	0.020	0.032	0.039
b2	1.143	1.27	1.778	0.045	0.050	0.070
c	0.381	0.50	0.737	0.015	0.020	0.029
c2	1.143	1.27	1.651	0.045	0.050	0.065
D	8.382	9.14	9.652	0.330	0.360	0.380
D1	6.858	8.00	8.37	0.270	0.315	0.330
e		2.54 BSC			0.100 BSC.	
E	9.652	10.03	10.668	0.380	0.395	0.420
E1	6.223	8.00	8.37	0.245	0.315	0.330
H	14.605	15.24	15.875	0.575	0.600	0.625
L	1.778	2.54	2.794	0.070	0.100	0.110
L1	1.02	1.27	1.676	0.040	0.050	0.066
L2	1.27	1.52	1.778	0.50	0.60	0.070
L3		0.25 BSC			0.010 BSC.	

NOTE:
1. PACKAGE BODY SIDES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH SHOULD BE LESS THAN 6 MILS.
2. TOLERANCE 0.10 MILLIMETERS UNLESS OTHERWISE SPECIFIED.
3. DIMENSION L IS MEASURED IN GAUGE LINE.
4. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.
5. REFER TO JEDEC TO-263 AB.